

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claim 1 (currently amended). A method for contact-connecting an electrical component on a substrate having a conductor structure, which comprises the steps of:

introducing a bonding agent between the electrical component and the conductor structure of the substrate, the bonding agent having a melting point being at a temperature at which the substrate is not damaged; and

producing a permanent electrically conductive connection by ~~melting the bonding agent and the bonding agent subsequently solidifying~~ by the steps of:

melting the bonding agent by heating the bonding agent to the melting point;

bringing the bonding agent to solidification;

increasing a joining temperature above a glass transition temperature of the substrate without causing the bonding agent to remelt; and

exerting a pressure on the electrical component resulting in the substrate experiencing a plastic deformation and the electrical component being pressed together with the conductor structure into the substrate in a positively locking manner, and the bonding agent being brought to solidification to form a rigid electric contact before the plastic deformation of the substrate takes place.

Claim 2 (original). The method according to claim 1, which further comprises:

forming the conductor structure with at least one conductor track and at least one contact point; and

introducing the bonding agent between a contact of the electrical component and the contact point of the conductor track.

Claim 3 (original). The method according to claim 1, which further comprises forming the substrate from a soft material having a melting point below 120° C.

Claim 4 (original). The method according to claim 3, which further comprises forming the substrate from a material selected from the group consisting of PVC and PET.

Claim 5 (original). The method according to claim 1, which further comprises forming the bonding agent from a solder material made of at least two different elementary metals or semiconductor materials.

Claim 6 (original). The method according to claim 5, which further comprises forming the solder material from bismuth.

Claim 7 (original). The method according to claim 5, which further comprises forming the solder material from a composition containing bismuth and indium, a composition containing bismuth and tin, or a composition containing indium and tin.

Claim 8 (original). The method according to claim 7, which further comprises forming the solder material from an intermetallic compound, a phase of a composition of  $\text{BiIn}$ , or a phase of a composition of  $\text{BiIn}_2$ .

Claim 9 (original). The method according to claim 1, which further comprises using a thermoplastic adhesive as the bonding agent.

Claim 10 (original). The method according to claim 1, which further comprises heating the electrical component and the substrate with a laser operating in an infrared region, which acts through the substrate in a direction of the electrical component.

Claim 11 (original). The method according to claim 1, which further comprises providing a semiconductor component as the electrical component.

Claim 12 (currently amended). A method for contact-connecting an electrical component on a substrate having a conductor structure, which comprises the steps of:

introducing a bonding agent between the electrical component and the conductor structure of the substrate, the bonding agent having a melting point being at a temperature at which the substrate is not damaged;

heating the electrical component, the substrate and the bonding agent to a joining temperature above a glass

transition temperature of the substrate for melting the bonding agent; and

bringing the bonding agent to solidification; and

exerting a pressure on the electrical component, ~~during which time the bonding agent solidifies, and~~ diffusing heat being ~~transferred~~ to the substrate from at least the bonding agent resulting in the substrate experiencing a plastic deformation and the electrical component being pressed together with the conductor structure into the substrate in a positively locking manner for forming a permanent electrical conductive connection, the bonding agent remaining in a solid state during the diffusion of the heat.

Claim 13 (new). The method according to claim 1, wherein the bonding agent is a solder material, the melting point of which increases during the soldering process.

Claim 14 (new). The method according to claim 1, wherein the bonding agent is a thermoplastic adhesive that solidifies before the plastic deformation of the substrate.